



PRELIMINARY SPECIFICATION

Part No.: _____
Customer: _____
Date: Oct.21, 2013

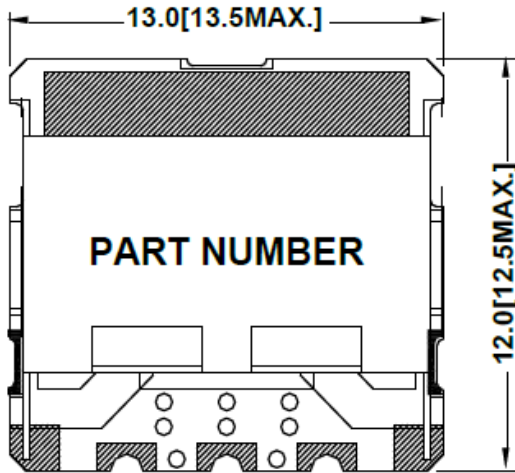
Written by	Checked by	Approval

ELECTRICAL SPECIFICATIONS

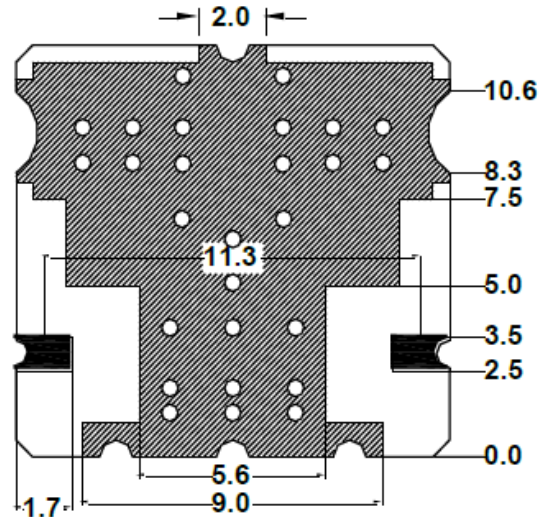
ITEM	SPEC	UNIT
1	Center freq	5800.0
2	Bandwidth [1dB BW]	fo ±75.0 [5725.0~5875.0]
3	Insertion Loss in BW	2.0
4	Ripple in BW	1.0
5	Return Loss in BW	15.0
6	V S W R in BW	max.
7	Attenuation (Absolute Value)	30.0 dB min. @ fo ± 400.0 [5400.0 & 6200.0]
8	Group Delay Variation	ns max
9	Input Power	2.0
10	In/Out Impedance	50Ω
11	Operation Temperature Range	-40°C to +85°C

MECHANICAL SPECIFICATIONS

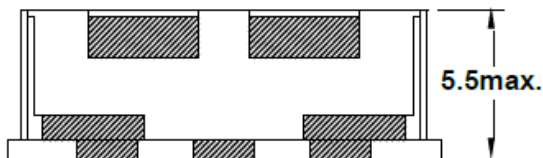
TOP VIEW




BOTTOM VIEW



FRONT VIEW



 I/O PORT

 GROUND

TOLERANCE: ± 0.2

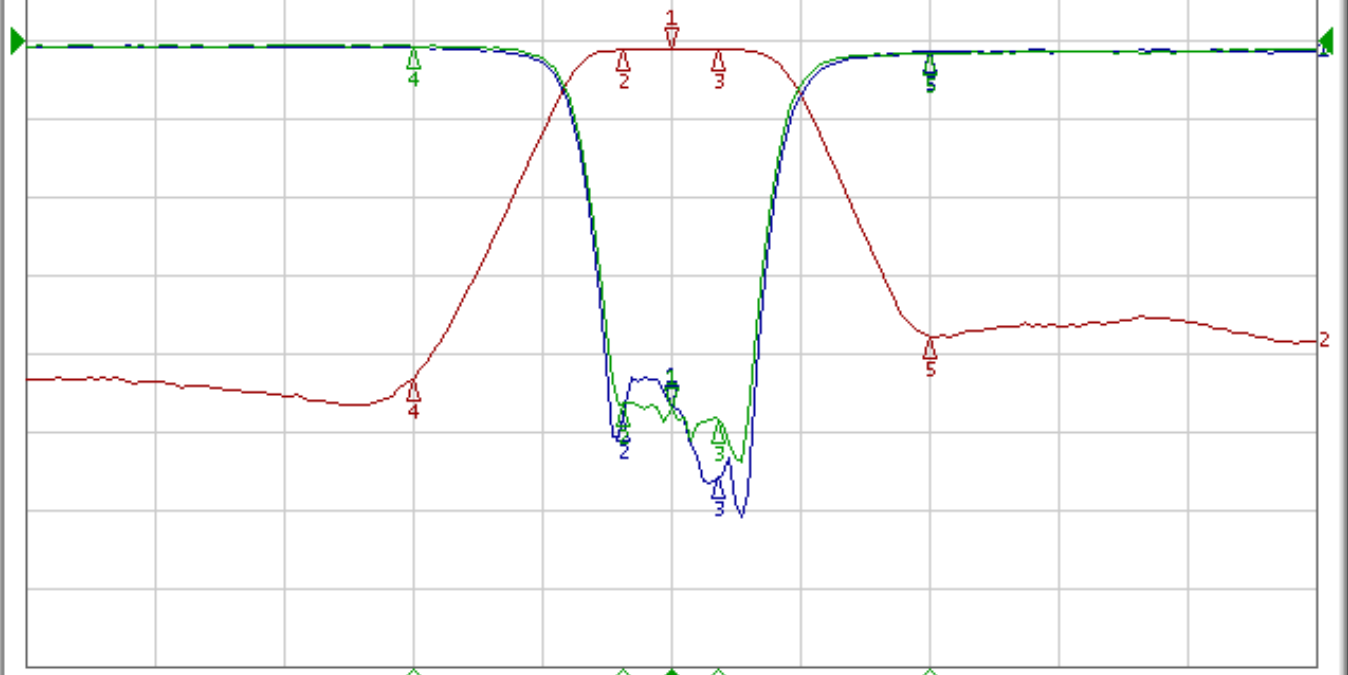
UNIT: mm

PLOT DATA

1 Active Ch/Trace 2 Response 3 Stimulus 4 Mkr/Analysis 5 Instr State

Tr1 S11 Log Mag 5.000dB/ Ref 0.000dB [F2]
Tr2 S21 Log Mag 10.00dB/ Ref 0.000dB [F2]
Tr3 S22 Log Mag 5.000dB/ Ref 0.000dB [F2]

1	5.8000000 GHz	-0.9695 dB
2	5.7250000 GHz	-1.0800 dB
3	5.8750000 GHz	-0.9998 dB
4	5.4000000 GHz	-43.160 dB
5	6.2000000 GHz	-37.737 dB

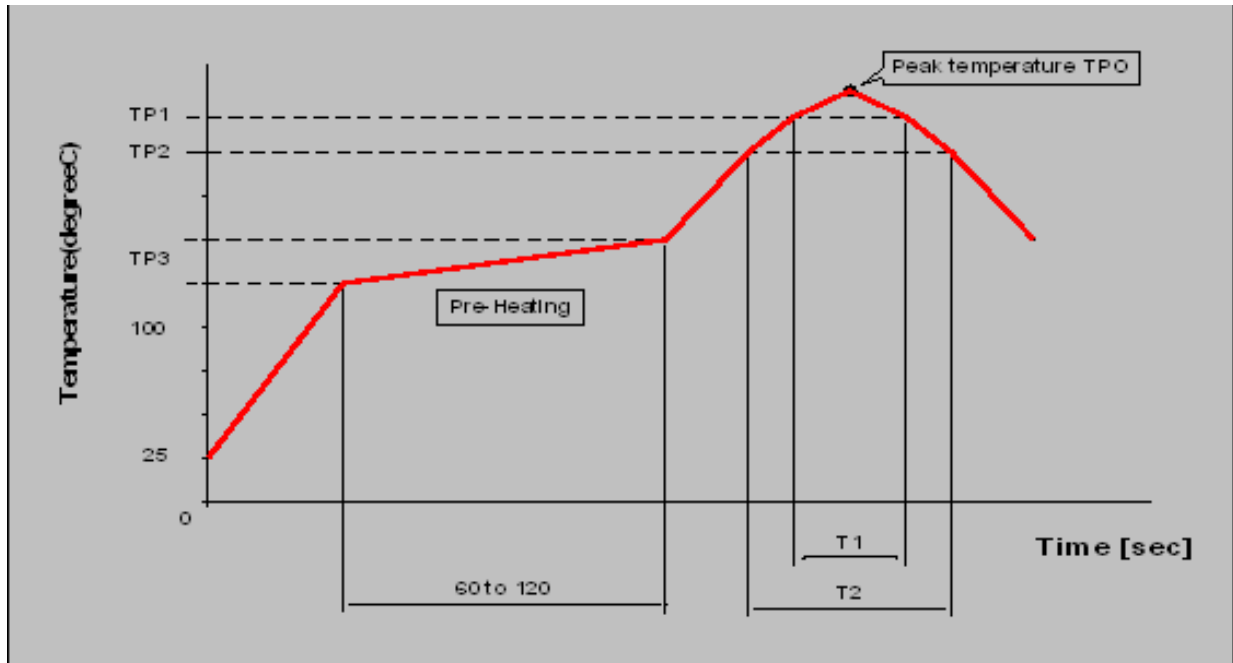


1 Center 5.8 GHz

IFBW 70 kHz

Span 2 GHz Cor !

SOLDERING CONDITION



Measuring point of temperature : IN OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 ()	TP1 ()	T1 (s)	TP2 ()	T2 (s)	TP3 ()
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180